

Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
 Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, Aug 09, 2014 03:13 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FSAM15SH60A	FSAM15SH60A	SPM32-AA			INTERNAL SUZHOU	31.601660	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance * Accepted
<p>Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p>		
Exemption List Version EL-2011/534/EU		
7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).		

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
--------------------	--

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SPM32-AA

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	67.700	Supplier		Silicon	67.700	7440-21-3	2142
Die Attach Epoxy	Other Organic Materials	14.360	Supplier		Phenolic resin	2.160	54208-63-8	68
			Supplier		Silver	12.200	7440-22-4	386
Die Attach Solder	Other Nonferrous metals & alloys	150.000	A	Lead/Lead Compounds	Lead	132.000	7439-92-1	4177
			Supplier		Silver	3.000	7440-22-4	95
			Supplier		Tin	15.000	7440-31-5	475
Encapsulation	Thermoplastics	13000.000	B	Antimony/Antimony Compounds	Antimony Trioxide	130.000	1309-64-4	4114
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	130.000	6386-73-8	4114
			Supplier		Carbon Black	130.000	1333-86-4	4114
			Supplier		Epoxy Resin	1300.000	29690-82-2	41137
			Supplier		Silica, vitreous	11310.000	60676-86-0	357893
Heat Sink	Aluminum & its alloys	5920.000	Supplier		Aluminum Oxide	5920.000	1344-28-1	187332
Lead Frame	Copper & its alloys	12303.900	Supplier		Copper	12280.000	7440-50-8	388587
			Supplier		Iron	14.800	7439-89-6	468
			Supplier		Phosphorus	4.920	7723-14-0	156
			Supplier		Silver	4.180	7440-22-4	132
Plating	Other Nonferrous metals & alloys	110.000	Supplier		Tin	110.000	7440-31-5	3481
Wire Bond	Precious metals	35.700	Supplier		Aluminum	34.000	7429-90-5	1076
			Supplier		Gold	1.700	7440-57-5	54